



Final Product Change Notification

201703018F01

Issue Date: 25-Jul-2017
Effective Date: 23-Oct-2017
Dear *Tracy Hoglin*,

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input checked="" type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

PCN: MC9S12G128 and MC9S12G96 FAB EXPANSION (ATMC to TSMC3)

Details of this Change

NXP Semiconductors is announcing the introduction of Taiwan Semiconductor Manufacturing Company Fab 3 (TSMC3), Hsinchu, Taiwan as a dual source wafer manufacturing location for the MC9S12G128 and MC9S12G96.

NXP Semiconductors encourages the use of Flex part numbers to maximize supply continuity. Without the use of Flex part numbers, backlog will have to be converted from one fab sourced device to another fab sourced device as capacity dictates.

Key Dates TSMC3 Expansion

Qualified Samples: Available 28-July-2017 - K part numbers

PPAP: Available 11-August-2017

Effective Date / Backlog Conversion to Flex part number: Available October 2017 - Earlier approval/conversion can be supported

The Data Sheet for MC9S12G128 and MC9S12G96 has been updated by adding the TSMC3 mask set (0N42V) and Part ID information into Table 1-5.

The Errata has been updated to Rev. July 18, 2017. The errata "MC9S12G128, Mask 0N51A and 0N42V"

covers both 0N51A maskset and 0N42V.

The MC9S12G128 and MC9S12G96 Data Sheet and Errata can be found at http://www.nxp.com/products/automotive-products/microcontrollers-and-processors/16-bit-s12-s12x-mcus/ultra-reliable-s12g-general-purpose-automotive-and-industrial-microcontrollers:S12G?fpsp=1&tab=Documentation_Tab&lang_cd=en

Why do we Implement this Change

The Fab manufacturing site capacity expansion to TSMC3 will improve NXP's ability to meet increasing customer demand and still maintain supply from the original Fab (ATMC).

Identification of Affected Products

Top side marking

The Mask ID marking will change from 0N51A to 0N42V.

Part number will change with the Maskset Identifier Digit Set to J instead of F.

Product Availability

Sample Information

Samples are available from 28-Jul-2017

Date above reflects Qualified samples.

Sample part refer to attachment file.

Production

Planned first shipment 17-Oct-2017

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Fab Expansion. No Depletion of Inventory required.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 24-Aug-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Meryl Bender

Position NXP AMP Commercial Marketing

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
S9S12G96FOCLL	935324481557	S9S12G96FOCLL	16BIT 96K FLASH	LQFP100	RFS	BL Auto Micro Processors
S9S12G128FOMLH	935314928557	S9S12G128FOMLH	Au 16BIT 128K FLASH	QFP64	RFS	BL Auto Micro Processors
S9S12G96FOMLL	935324446557	S9S12G96FOMLL	16BIT 96K FLASH	LQFP100	RFS	BL Auto Micro Processors
S9S12G128FOCLH	935324447557	S9S12G128FOCLH	16BIT 128K FLASH	QFP64	RFS	BL Auto Micro Processors
S9S12G128FOMLL	935318114557	S9S12G128FOMLL	16BIT 128K FLASH	LQFP100	RFS	BL Auto Micro Processors
S9S12G128FOCLL	935322126557	S9S12G128FOCLL	Au 16BIT 128K FLASH	LQFP100	RFS	BL Auto Micro Processors
S9S12G128FOMLF	935314492557	S9S12G128FOMLF	16BIT 128K FLASH	LQFP48	RFS	BL Auto Micro Processors